3.3V / 5V ECL Differential **Receiver/Driver with High** Gain

Description

The EP16VA is a world-class differential receiver/driver. The device is functionally equivalent to the EP16 and LVEP16 devices but with high gain output. Q_{HG} and $\overline{Q_{HG}}$ outputs have a DC gain several times larger than the DC gain of an EP16.

The V_{BB} pin, an internally generated voltage supply, is available to this device only. For single-ended input conditions, the unused differential input is connected to V_{BB} as a switching reference voltage. V_{BB} may also rebias AC coupled inputs. When used, decouple V_{BB} and V_{CC} via a 0.01 µF capacitor and limit current sourcing or sinking to 0.5 mA. When not used, V_{BB} should be left open.

Under open input conditions (pulled to V_{EE}) internal input clamps will force the Q_{HG} output LOW.

Special considerations are required for differential inputs under No Signal conditions to prevent instability.

The 100 Series contains temperature compensation.

Features

- 270 ps Typical Propagation Delay
- Gain > 20
- 20 mV Minimum Input Voltage Swing
- Maximum Frequency > 3 GHz Typical
- PECL Mode Operating Range: $V_{CC} = 3.0 \text{ V}$ to 5.5 V with $V_{EE} = 0 V$
- NECL Mode Operating Range: $V_{CC} = 0 V$ with $V_{EE} = -3.0$ V to -5.5 V
- Open Input Default State
- V_{BB} Output
- Pb-Free Packages are Available



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HEP64

ALYW

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HP64

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MARKING DIAGRAMS*

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KEP64

ALYW

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CASE 751



DT SUFFIX

CASE 948R









DFN8 **MN SUFFIX** CASE 506AA

Н	= MC10	А	= Assembly Location
Κ	= MC100	L	= Wafer Lot
5N	= MC10	Υ	= Year
3E	= MC100	W	= Work Week
М	= Date Code	•	= Pb-Free Package

(Note: Microdot may be in either location)

*For additional marking information, refer to Application Note AND8002/D.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 8 of this data sheet.

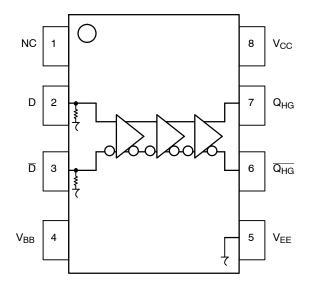


Table 1. PIN DESCRIPTION

PIN	FUNCTION
D*, <u>D</u> *	ECL Data Inputs
Q _{HG} , Q _{HG}	ECL High Gain Data Outputs
V _{BB}	Reference Voltage Output
V _{CC}	Positive Supply
V _{EE}	Negative Supply
NC	No Connect
EP	(DFN8 only) Thermal exposed pad must be connected to a sufficient thermal conduit. Electrically connect to the most negative supply (GND) or leave unconnected, floating open.

* Pins will default LOW when left open.

Figure 1. 8-Lead Pinout (Top View) and Logic Diagram

C	haracteristics	Va	lue				
Internal Input Pulldown Re	nternal Input Pulldown Resistor						
Internal Input Pullup Resis	Ν	/A					
ESD Protection	ESD Protection Human Body Model Machine Model Charged Device Model						
Moisture Sensitivity, Indefi	nite Time Out of Drypack (Note 1)	Pb Pkg	Pb-Free Pkg				
	SOIC-8 TSSOP-8 DFN8	Level 1 Level 1 Level 1	Level 1 Level 3 Level 1				
Flammability Rating	Oxygen Index: 28 to 34	UL-94 V-0	@ 0.125 in				
Transistor Count	10	67					
Meets or exceeds JEDEC	Spec EIA/JESD78 IC Latchup Test						

Table 2. ATTRIBUTES

1. For additional information, see Application Note AND8003/D.

Table 3. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V _{CC}	PECL Mode Power Supply	V _{EE} = 0 V		6	V
V_{EE}	NECL Mode Power Supply	$V_{CC} = 0 V$		-6	V
VI	PECL Mode Input Voltage NECL Mode Input Voltage	V _{EE} = 0 V V _{CC} = 0 V	$\begin{array}{c} V_{I} \leq V_{CC} \\ V_{I} \geq V_{EE} \end{array}$	6 -6	V V
l _{out}	Output Current	Continuous Surge		50 100	mA mA
I _{BB}	V _{BB} Sink/Source			± 0.5	mA
T _A	Operating Temperature Range			-40 to +85	°C
T _{stg}	Storage Temperature Range			-65 to +150	°C
θ_{JA}	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	8 SOIC 8 SOIC	190 130	°C/W °C/W
θ_{JC}	Thermal Resistance (Junction-to-Case)	Standard Board	8 SOIC	41 to 44	°C/W
θ_{JA}	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	8 TSSOP 8 TSSOP	185 140	°C/W °C/W
θ_{JC}	Thermal Resistance (Junction-to-Case)	Standard Board	8 TSSOP	41 to 44	°C/W
θ_{JA}	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	DFN8 DFN8	129 84	°C/W °C/W
T _{sol}	Wave Solder Pb Pb-Free	<2 to 3 sec @ 248°C <2 to 3 sec @ 260°C		265 265	°C
θ_{JC}	Thermal Resistance (Junction-to-Case)	(Note 2)	DFN8	35 to 40	°C/W

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

2. JEDEC standard multilayer board - 2S2P (2 signal, 2 power)

Table 4. 10EP DC CHARACTERISTICS, PECL V_{CC} = 3.3 V, V_{EE} = 0 V (Note 3)

			−40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I _{EE}	Power Supply Current	20	28	36	22	30	38	24	32	40	mA
V _{OH}	Output HIGH Voltage (Note 4)	2165	2240	2415	2230	2355	2480	2290	2415	2540	mV
V _{OL}	Output LOW Voltage (Note 4)	1365	1490	1615	1430	1555	1680	1490	1615	1740	mV
V _{IH}	Input HIGH Voltage (Single-Ended)	2090		2415	2155		2480	2215		2540	mV
V _{IL}	Input LOW Voltage (Single-Ended)	1365		1690	1460		1755	1490		1815	mV
V_{BB}	Output Voltage Reference	1790	1950	1990	1855	2000	2055	1915	2040	2115	mV
VIHCMR	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 5)	2.0		3.3	2.0		3.3	2.0		3.3	V
IIH	Input HIGH Current			150			150			150	μΑ
IIL	Input LOW Current	0.5			0.5			0.5			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

3. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary +0.3 V to –2.2 V.

4. All loading with 50 Ω to V_{CC} – 2.0 V.

V_{IHCMR} min varies 1:1 with V_{EE}, V_{IHCMR} max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

			-40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I_{EE}	Power Supply Current	20	28	36	22	30	38	24	32	40	mA
V _{OH}	Output HIGH Voltage (Note 7)	3865	3940	4115	3930	4055	4180	3990	4115	4240	mV
V _{OL}	Output LOW Voltage (Note 7)	3065	3190	3315	3130	3255	3380	3190	3315	3440	mV
VIH	Input HIGH Voltage (Single-Ended)	3790		4115	3855		4180	3915		4240	mV
V _{IL}	Input LOW Voltage (Single-Ended)	3065		3390	3130		3455	3190		3515	mV
V_{BB}	Output Voltage Reference	3490	3633	3690	3555	3670	3755	3615	3710	3815	mV
VIHCMR	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 8)	2.0		5.0	2.0		5.0	2.0		5.0	V
I _{IH}	Input HIGH Current			150			150			150	μA
IIL	Input LOW Current	0.5			0.5			0.5			μA

Table 5. 10EP DC CHARACTERISTICS, PECL V_{CC} = 5.0 V, V_{EE} = 0 V (Note 6)

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

6. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary +2.0 V to –0.5 V.

7. All loading with 50 Ω to V_{CC} – 2.0 V.

8. V_{IHCMR} min varies 1:1 with V_{EE}, V_{IHCMR} max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

			-40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I _{EE}	Power Supply Current	20	28	36	22	30	38	24	32	40	mA
V _{OH}	Output HIGH Voltage (Note 10)	-1135	-1060	-885	-1070	-945	-820	-1010	-885	-760	mV
V _{OL}	Output LOW Voltage (Note 10)	-1935	-1810	-1685	-1870	-1745	-1620	-1810	-1685	-1560	mV
V _{IH}	Input HIGH Voltage (Single-Ended)	-1210		-885	-1145		-820	-1085		-760	mV
V _{IL}	Input LOW Voltage (Single-Ended)	-1935		-1610	-1870		-1545	-1810		-1485	mV
V _{BB}	Output Voltage Reference	-1510	-1367	-1310	-1445	-1330	-1245	-1385	-1290	-1185	mV
VIHCMR	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 11)	V _{EE}	+2.0	0.0	V _{EE}	+2.0	0.0	V _{EE}	+2.0	0.0	V
I _{IH}	Input HIGH Current			150			150			150	μA
IIL	Input LOW Current	0.5			0.5			0.5			μΑ

Table 6. 10EP DC CHARACTERISTICS, NECL V_{CC} = 0 V; V_{EE} = -5.5 V to -3.0 V (Note 9)

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

9. Input and output parameters vary 1:1 with V_{CC} .

10. All loading with 50 Ω to V_{CC} – 2.0 V.

11. V_{IHCMR} min varies 1:1 with V_{EE}, V_{IHCMR} max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

			-40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I_{EE}	Power Supply Current	22	28	36	24	30	40	26	32	42	mA
V _{OH}	Output HIGH Voltage (Note 13)	2155	2280	2405	2155	2280	2405	2155	2280	2405	mV
V _{OL}	Output LOW Voltage (Note 13)	1305	1430	1555	1305	1430	1555	1305	1430	1555	mV
VIH	Input HIGH Voltage (Single-Ended)	2075		2420	2075		2420	2075		2420	mV
VIL	Input LOW Voltage (Single-Ended)	1355		1675	1355		1675	1355		1675	mV
V_{BB}	Output Voltage Reference	1775	1875	1975	1775	1875	1975	1775	1875	1975	mV
VIHCMR	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 14)	2.0		3.3	2.0		3.3	2.0		3.3	V
I _{IH}	Input HIGH Current			150			150			150	μA
IIL	Input LOW Current	0.5			0.5			0.5			μA

Table 7. 100EP DC CHARACTERISTICS, PECL V_{CC} = 3.3 V, V_{EE} = 0 V (Note 12)

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

12. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary +0.3 V to -2.2 V.

13. All loading with 50 Ω to V_{CC} – 2.0 V.

14. V_{IHCMR} min varies 1:1 with V_{EE}, V_{IHCMR} max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

			–40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I _{EE}	Power Supply Current	22	28	36	24	30	40	26	32	42	mA
V _{OH}	Output HIGH Voltage (Note 16)	3855	3980	4105	3855	3980	4105	3855	3980	4105	mV
V _{OL}	Output LOW Voltage (Note 16)	3005	3180	3355	3005	3180	3355	3005	3180	3355	mV
VIH	Input HIGH Voltage (Single-Ended)	3775		4120	3775		4120	3775		4120	mV
VIL	Input LOW Voltage (Single-Ended)	3055		3375	3055		3375	3055		3375	mV
V_{BB}	Output Voltage Reference	3475	3575	3675	3475	3575	3675	3475	3575	3675	mV
VIHCMR	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 17)	2.0		5.0	2.0		5.0	2.0		5.0	V
I _{IH}	Input HIGH Current			150			150			150	μA
IIL	Input LOW Current	0.5			0.5			0.5			μA

Table 8. 100EP DC CHARACTERISTICS, PECL V_{CC} = 5.0 V, V_{EE} = 0 V (Note 15)

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

15. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary +2.0 V to –0.5 V.

16. All loading with 50 Ω to V_CC – 2.0 V.

17. V_{IHCMR} min varies 1:1 with V_{EE}, V_{IHCMR} max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

			−40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I_{EE}	Power Supply Current	22	28	36	24	30	40	26	32	42	mA
V _{OH}	Output HIGH Voltage (Note 19)	-1145	-1020	-895	-1145	-1020	-895	-1145	-1020	-895	mV
V _{OL}	Output LOW Voltage (Note 19)	-1995	-1870	-1745	-1995	-1870	-1745	-1995	-1870	-1745	mV
VIH	Input HIGH Voltage (Single-Ended)	-1225		-880	-1225		-880	-1225		-880	mV
VIL	Input LOW Voltage (Single-Ended)	-1945		-1625	-1945		-1625	-1945		-1625	mV
V_{BB}	Output Voltage Reference	-1525	-1425	-1325	-1525	-1425	-1325	-1525	-1425	-1325	mV
VIHCMR	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 20)	V _{EE}	+2.0	0.0	V _{EE}	+2.0	0.0	V _{EE}	+2.0	0.0	V
I _{IH}	Input HIGH Current			150			150			150	μA
IIL	Input LOW Current	0.5			0.5			0.5			μA

Table 9. 100EP DC CHARACTERISTICS, NECL V_{CC} = 0 V; V_{EE} = -5.5 V to -3.0 V (Note 18)

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

18. Input and output parameters vary 1:1 with $V_{\mbox{CC}}.$

19. All loading with 50 Ω to V_{CC} – 2.0 V.

20. V_{IHCMR} min varies 1:1 with V_{EE}, V_{IHCMR} max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

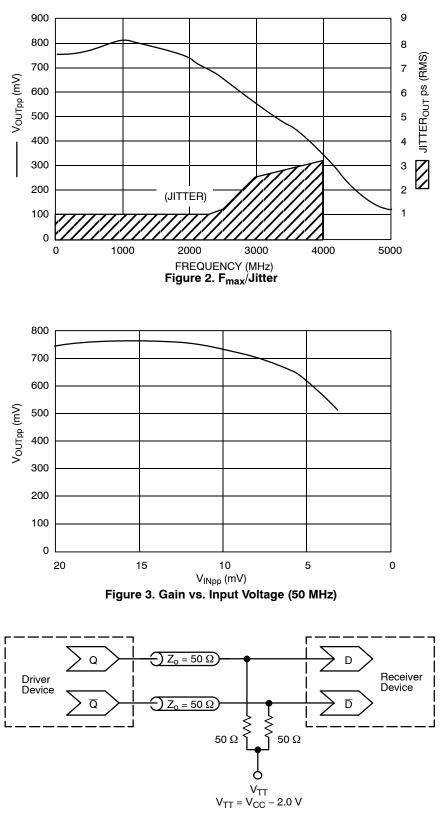
				-40°C			25°C		85°C			
Symbol	Characteristic		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
f _{max}	Maximum Frequency (See Figure 2 F _{max} /JITTER)			> 3			> 3			> 3		GHz
t _{PLH} , t _{PHL}	Propagation Delay to Output Differential		200	260	320	220	270	340	250	320	390	ps
t _{SKEW}	Duty Cycle Skew (Note 22)			5.0	20		5.0	20		5.0	20	ps
t JITTER	Cycle-to-Cycle Jitter (See Figure 2 F _{max} /JITTER)			0.2	< 1		0.2	< 1		0.2	< 1	ps
V _{PP}	Input Voltage Swing (Differential Configuration) (See Figure 3)		20	800	120 0	20	800	120 0	20	800	120 0	mV
t _r t _f	Output Rise/Fall Times (20% – 80%)	Q,	70	110	170	80	110	180	80	120	200	ps

Table 10. AC CHARACTERISTICS $V_{CC} = 0 V$; $V_{EE} = -3.0 V$ to -5.5 V or $V_{CC} = 3.0 V$ to 5.5 V; $V_{EE} = 0 V$ (Note 21)

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

21. Measured using a 750 mV source, 50% duty cycle clock source. All loading with 50 Ω to V_{CC}-2.0 V.

22. Skew is measured between outputs under identical transitions. Duty cycle skew is defined only for differential operation when the delays are measured from the cross point of the inputs to the cross point of the outputs.





ORDERING INFORMATION

Device	Package	Shipping [†]
MC10EP16VAD	SOIC-8	98 Units / Rail
MC10EP16VADG	SOIC-8 (Pb-Free)	98 Units / Rail
MC10EP16VADR2	SOIC-8	2500 / Tape & Reel
MC10EP16VADR2G	SOIC-8 (Pb-Free)	2500 / Tape & Reel
MC10EP16VADT	TSSOP-8	100 Units / Rail
MC10EP16VADTG	TSSOP-8 (Pb-Free)	100 Units / Rail
MC10EP16VADTR2	TSSOP-8	2500 / Tape & Reel
MC10EP16VADTR2G	TSSOP-8 (Pb-Free)	2500 / Tape & Reel
MC10EP16VAMNR4	DFN8	1000 / Tape & Reel
MC10EP16VAMNR4G	DFN8 (Pb-Free)	1000 / Tape & Reel
MC100EP16VAD	SOIC-8	98 Units / Rail
MC100EP16VADG	SOIC-8 (Pb-Free)	98 Units / Rail
MC100EP16VADR2	SOIC-8	2500 / Tape & Reel
MC100EP16VADR2G	SOIC-8 (Pb-Free)	2500 / Tape & Reel
MC100EP16VADT	TSSOP-8	100 Units / Rail
MC100EP16VADTG	TSSOP-8 (Pb-Free)	100 Units / Rail
MC100EP16VADTR2	TSSOP-8	2500 / Tape & Reel
MC100EP16VADTR2G	TSSOP-8 (Pb-Free)	2500 / Tape & Reel
MC100EP16VAMNR4	DFN8	1000 / Tape & Reel
MC100EP16VAMNR4G	DFN8 (Pb–Free)	1000 / Tape & Reel

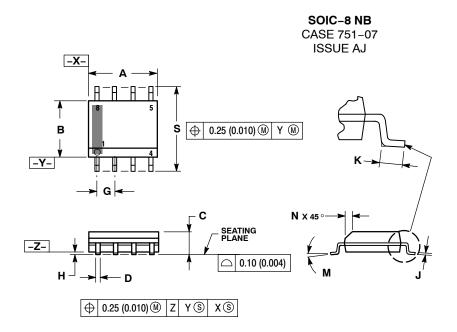
+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Resource Reference of Application Notes

AN1405/D	-	ECL Clock Distribution Techniques
AN1406/D	_	Designing with PECL (ECL at +5.0 V)
AN1503/D	-	ECLinPS [™] I/O SPiCE Modeling Kit
AN1504/D	-	Metastability and the ECLinPS Family
AN1568/D	-	Interfacing Between LVDS and ECL
AN1672/D	_	The ECL Translator Guide
AND8001/D	-	Odd Number Counters Design

- AND8002/D Marking and Date Codes
- AND8020/D Termination of ECL Logic Devices
- AND8066/D Interfacing with ECLinPS
- AND8090/D AC Characteristics of ECL Devices

PACKAGE DIMENSIONS



NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETER.

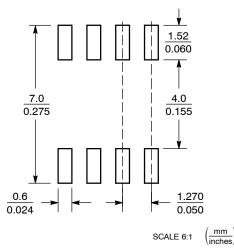
DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION. З.

MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TEF AUTURN TO PADO TET NEW

751–01 THRU 751–06 ARE OBSOLETE. NEW STANDARD IS 751–07. 6.

	MILLIN	IETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	4.80	5.00	0.189	0.197	
В	3.80	4.00	0.150	0.157	
С	1.35	1.75	0.053	0.069	
D	0.33	0.51	0.013	0.020	
G	1.27	7 BSC	0.05	0 BSC	
Н	0.10	0.25	0.004	0.010	
J	0.19	0.25	0.007	0.010	
Κ	0.40	1.27	0.016	0.050	
М	0 °	8 °	0 °	8 °	
Ν	0.25	0.50	0.010	0.020	
S	5.80	6.20	0.228	0.244	

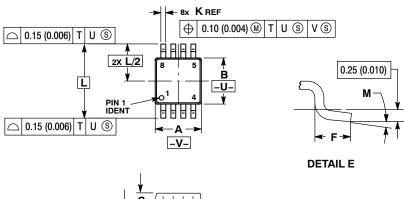
SOLDERING FOOTPRINT*

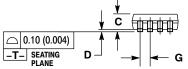


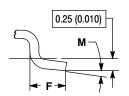
*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

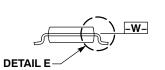
PACKAGE DIMENSIONS

TSSOP-8 DT SUFFIX PLASTIC TSSOP PACKAGE CASE 948R-02 **ISSUE A**









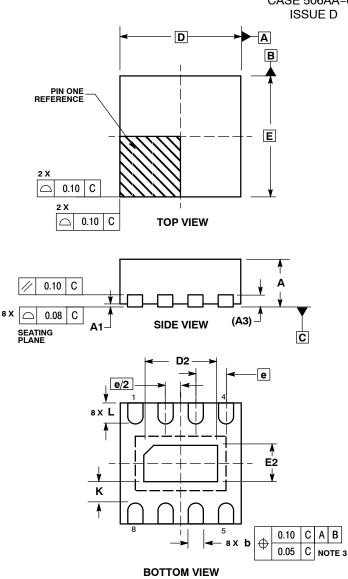
NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI
Y14.5M, 1982.

- Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER.
 DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
 TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
 DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

	MILLIN	IETERS	INCHES	
DIM	MIN	MAX	MIN	MAX
Α	2.90	3.10	0.114	0.122
В	2.90	3.10	0.114	0.122
С	0.80	1.10	0.031	0.043
D	0.05	0.15	0.002	0.006
F	0.40	0.70	0.016	0.028
G	0.65	BSC	0.026 BSC	
Κ	0.25	0.40	0.010	0.016
L	4.90	BSC	0.193 BSC	
М	0°	6 °	0°	6°

PACKAGE DIMENSIONS

DFN8 CASE 506AA-01



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994 . 2. CONTROLLING DIMENSION: MILLIMETERS.

- DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL.
 COPLANARITY APPLIES TO THE EXPOSED
- PAD AS WELL AS THE TERMINALS.

	MILLIMETERS		
DIM	MIN	MAX	
Α	0.80	1.00	
A1	0.00	0.05	
A3	0.20 REF		
b	0.20	0.30	
D	2.00 BSC		
D2	1.10	1.30	
E	2.00 BSC		
E2	0.70	0.90	
е	0.50 BSC		
к	0.20		
L	0.25	0.35	

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